

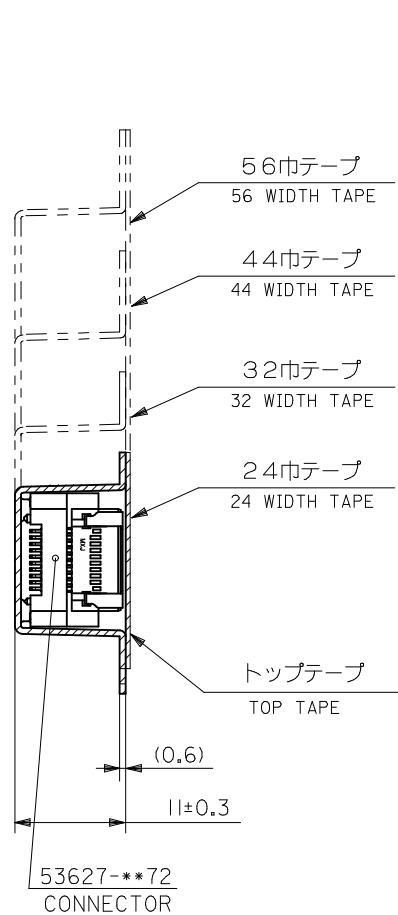
NOTES

1. 材質
MATERIAL
ハウジング: ガラス入りPPS、茶色、UL94V-0
HOUSING: POLYPHENYLENE SULFIDE, GLASS FILLED, BROWN, UL94V-0
ターミナル: 銅合金 (t=0.2)、ニッケルメッキ下地1.0マイクロメートル以上
TERMINAL: COPPER ALLOY, UNDER-PLATING: NICKEL 1.5 MICROMETER MIN.
接点部 : 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MIN.
半田付け部 : 錫メッキ1.0マイクロメートル以上
SOLDER TAIL AREA: TIN 1.0 MICROMETER MIN.
ネール : リン青銅(t=0.2)、ニッケルメッキ下地1.0マイクロメートル以上
NAIL: PHOSPHOR BRONZE, UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.
鍍メッキ1.0マイクロメートル以上
TIN 1.0 MICROMETER MIN.
吸着カバー: ステンレス (t=0.2)
VACUUM COVER: STAINLESS STEEL

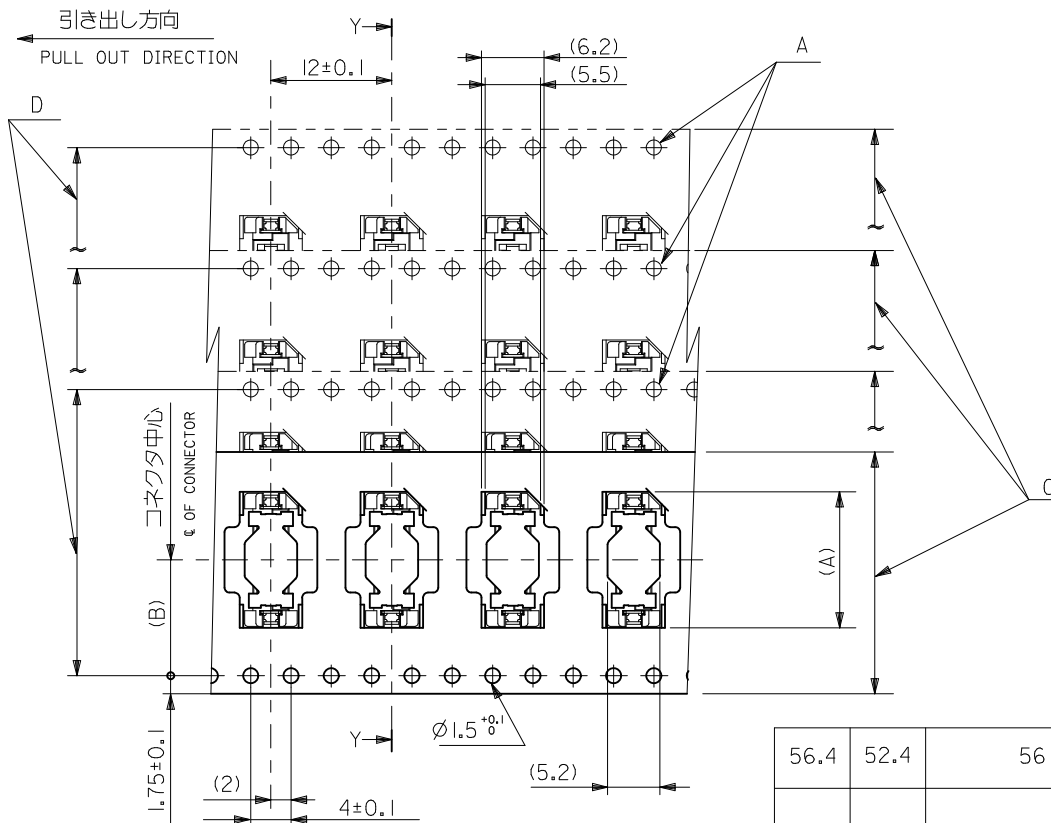
2. テールのバラツキ寸法
TAIL COPLANARITY
テール平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MILLIMETER MAX.

無し NO	66.47	65.37	62.865	70.37	53627-2074	—	200
	53.77	52.67	50.165	57.67	—	53627-1675	160
	47.42	46.32	43.815	51.32	53627-1474	-1475	140
	41.07	39.97	37.465	44.97	-1274	-1275	120
	34.72	33.62	31.115	38.62	-1074	-1075	100
有り YES	31.55	30.45	27.94	35.45	-0974	-0975	90
	28.37	27.27	24.765	32.27	-0874	-0875	80
	25.2	24.1	21.59	29.1	-0774	-0775	70
	22.02	20.92	18.415	25.92	-0674	-0675	60
	18.85	17.75	15.24	22.75	-0574	-0575	50
15.67	14.57	12.065	19.57	-0474	-0475	40	
12.5	11.4	8.89	16.4	-0374	-0375	30	
9.32	8.22	5.715	13.22	53627-0274	53627-0275	20	
ハウジングロック HS'G LOCK	D	C	B	A	エンボス梱包 EMBOSSED PACKAGE	スティック梱包 STICK PACKAGE	極数 CIRCUITS
CONNECTOR SERIES No.						53627-**72	

REVISED EC NO: J2010-2458 DRWN:TKAHO 2010/06/04 CHKD:M.SASAO 2010/06/10 APPR:MSASAO 2010/06/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY Y. SAKIYAMA	DATE 2004/03/05	TITLE 0.635 PITCH B/B CONN. PLUG HSG COVER ASSY -LEAD FREE-					
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/03/05	MOLEX INCORPORATED					
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/05	SEE CHART SD-53627-001					
ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO. 1 OF 1			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



断面 Y-Y
SECTION Y-Y

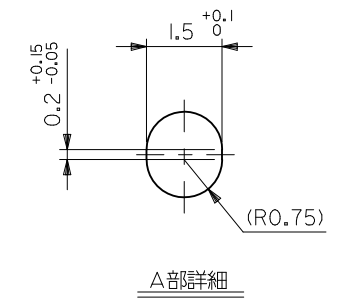
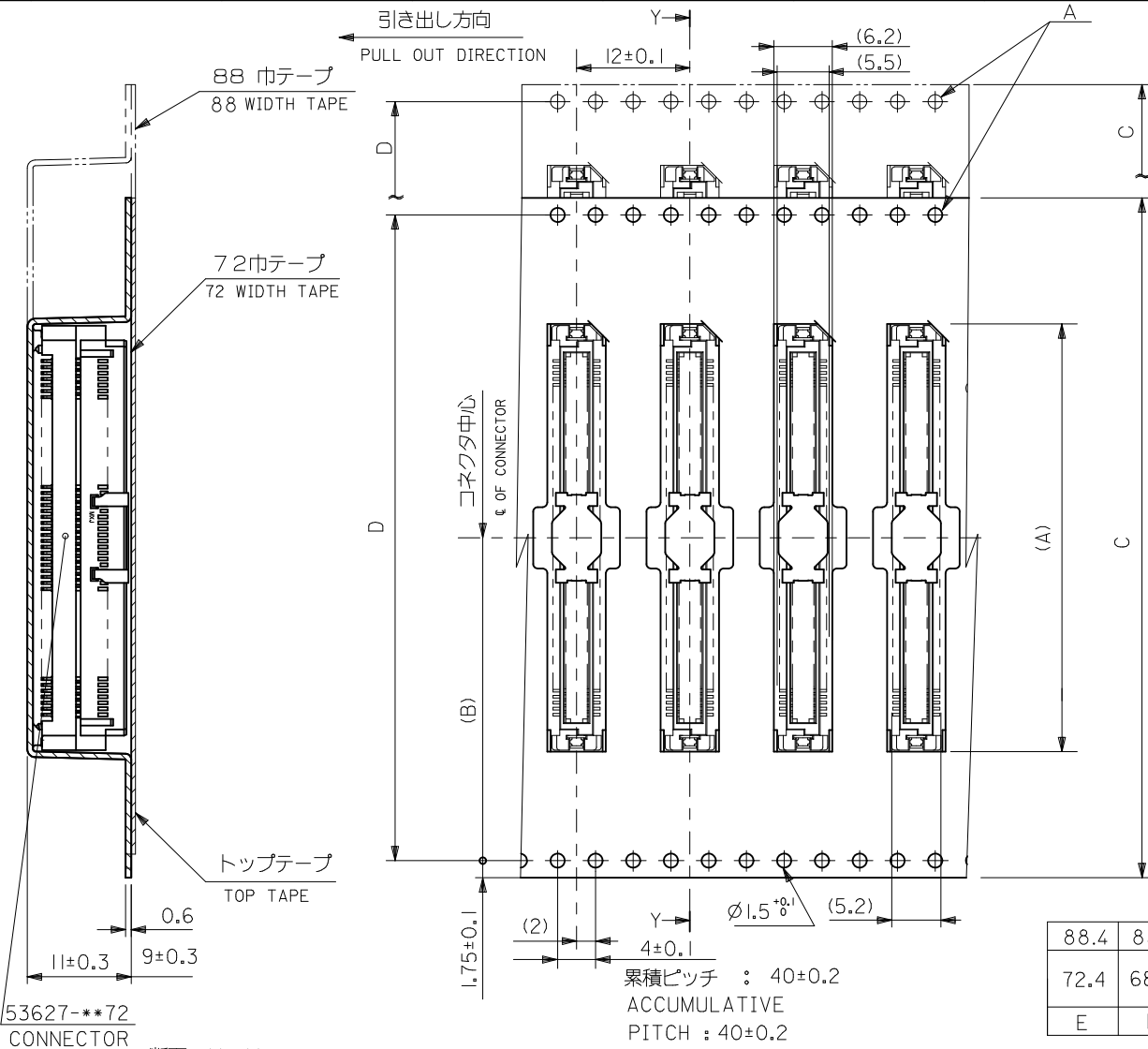


累積ピッチ : 40±0.2
ACCUMULATIVE
PITCH : 40±0.2

56.4	52.4	56	26.2	38.9	53627-1074	100
				35.8	-0974	90
44.4	40.4	44	20.2	32.6	-0874	80
				29.4	-0774	70
				26.2	-0674	60
				23.1	-0574	50
32.4	28.4	32	14.2	19.9	-0474	40
				16.7	-0374	30
24.4	—	24	11.5	13.5	53627-0274	20
E	D	C	キャリアテープ幅 CARRIER TAPE WIDTH	(B)	(A)	MATERIAL NO. 極数 CIRCUITS

REVISED EC NO: J2010-2458 DRWN:TKAIHO 2010/06/04 CH'KD:M.SASAO 2010/06/10 APPR:MSASAO 2010/06/11 REV: B	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. 53627-***72	
	10 UNDER	±0.2	DRAWN BY Y.SAKIYAMA		SCALE ---	
	10 OVER 30 UNDER	±0.25	DATE 2004/03/05		DESIGN UNITS METRIC	
	30 OVER	±0.3	CHECKED BY M.SASAO		THIRD ANGLE PROJECTION	
ANGULAR ±3 °		APPROVED BY M.SASAO		DATE 2004/03/05		TITLE EMBSTP PKG FOR 0.635 B/B PLUG HSG ASSY (H=10) -LEAD FREE- MOLEX INCORPORATED
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		
		SIZE A3		SEE CHART		SHEET NO. 2 OF 3

10 9 8 7 6 5 4 3 2 1



53627-***72
CONNECTOR
断面 Y-Y
SECTION Y-Y

88.4	84.4	88	42.2	70.7	53627-2074	200
72.4	68.4	72	34.2	51.6	53627-1474	140
				45.3	53627-1274	120
E	D	C	キャリアテープ幅 CARRIER TAPE WIDTH	(B)	(A)	MATERIAL NO. 種数 CIRCUITS

REVISED EC NO: J2010-2458 DRWN: KAIHO 2010/06/04 CHKD: M. SASAO 2010/06/10 APPR: MSASAO 2010/06/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. 53627-***72	
	10 UNDER	±0.2	DRAWN BY DATE Y. SAKIYAMA 2004/03/05		SCALE DESIGN UNITS --- METRIC	
	10 OVER 30 UNDER	±0.25	CHECKED BY DATE M. SASAO 2004/03/05		TITLE EMBSTP PKG FOR 0.635 B/B PLUG HSG ASSY (H=10) -LEAD FREE-	
	30 OVER	±0.3	APPROVED BY DATE M. SASAO 2004/03/05		MOLEX INCORPORATED	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53627-002
				SHEET NO. 3 OF 3		